

IC/ PC/LED 自動化設備
解決方案

AllRing Tech 萬潤科技簡介

Presented by Allring

About Us

Establish

May 24. 1996

Chairman

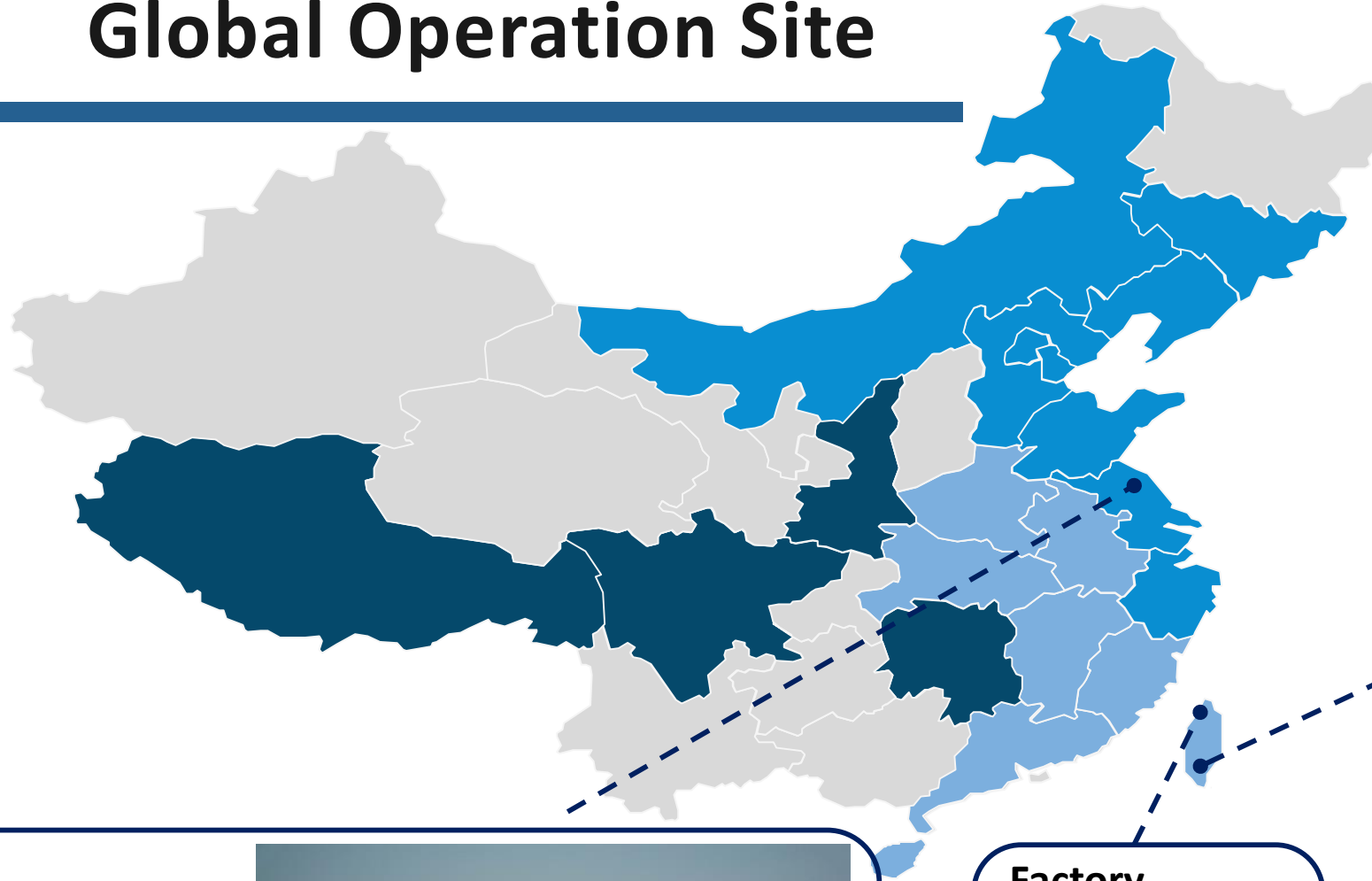
Larry Lu

Business

Automation equipment supplier for
Semiconductor test & package, Passive Component
manufacturing industries



Global Operation Site



Subsidiary

◆ Kunshan

Jiangsu

Factory Area:
20,000 m²



Factory

◆ Hsinchu

◆ Taichung

Headquarters

Kaohsiung/Taiwan

Factory Area: 27,000 m²

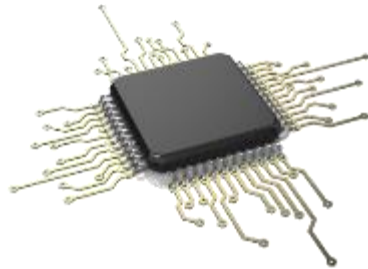


MILESTONE



1996

- Company Established
- Passive Component
- Automatic Cutting Machine
- Inductor Test & Packing Machine



2000

- Entered IC Industry



2004

- Entered Kaohsiung Industrial Science Park
- FDP Equip.
- PCB Inspect Machine
- FPD Dispenser



2008

- Developed LED equip.



2010

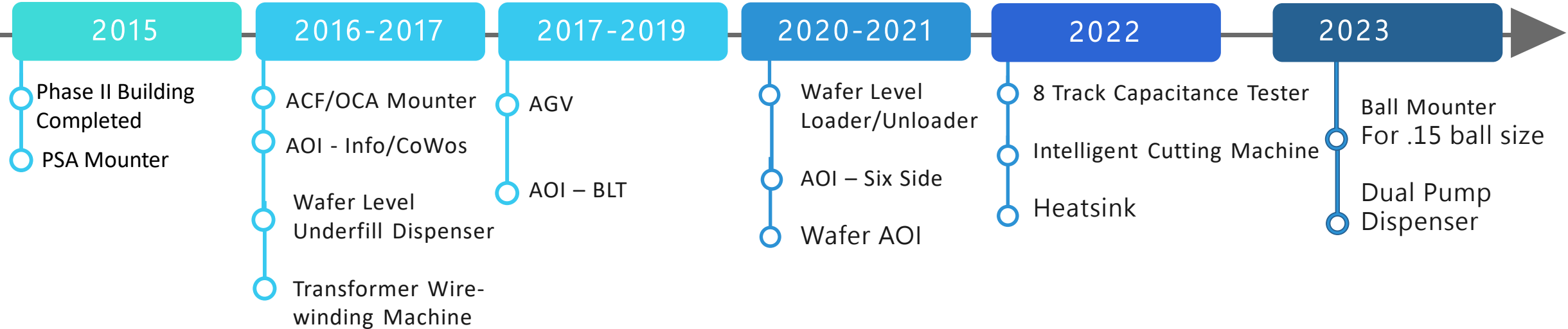
- Purchased Kunshan Plant
- Allring Charity Foundation Established



2013

- Started S.I.P
- R&D Center Established

MILESTONE

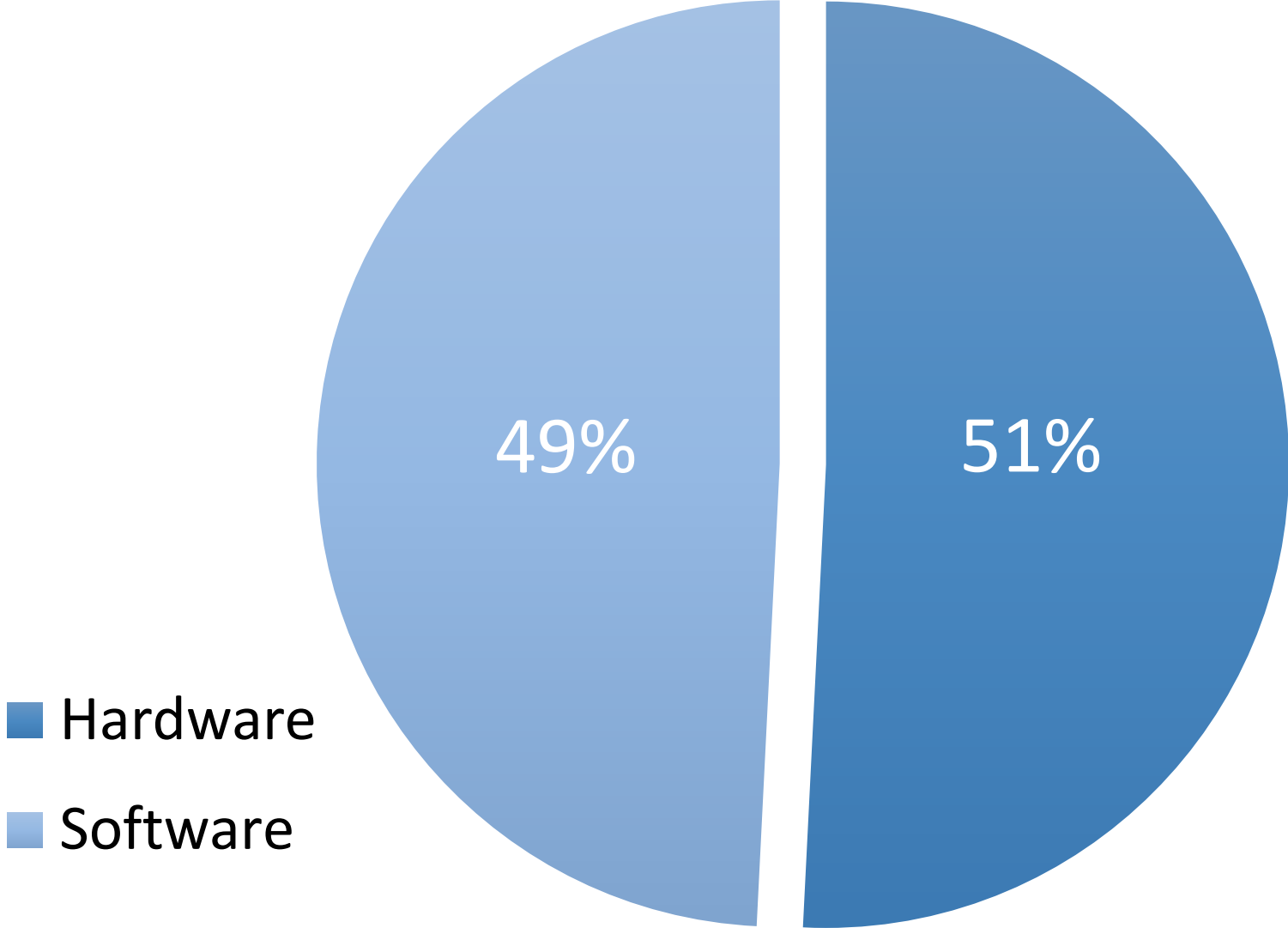


Human Resources R&D

60%

OF OUR 280 EMPLOYEES ARE
RESEARCH AND DEVELOPMENT

Human Resources R&D



Product Line



Automation

Loader/ unloader
Carrier Transfer
Lane Change
Ball Mounter



Attach

Flex
PSA
OCA
Film Tim
Metal Tim
PI Film



Dispenser

Underfill
Flux Jetting
Silver Paste
Heatsink



AOI

Post-Die Bond
Post-Dispenser
Post-Bumping
AOI and Sorting



PC/LED

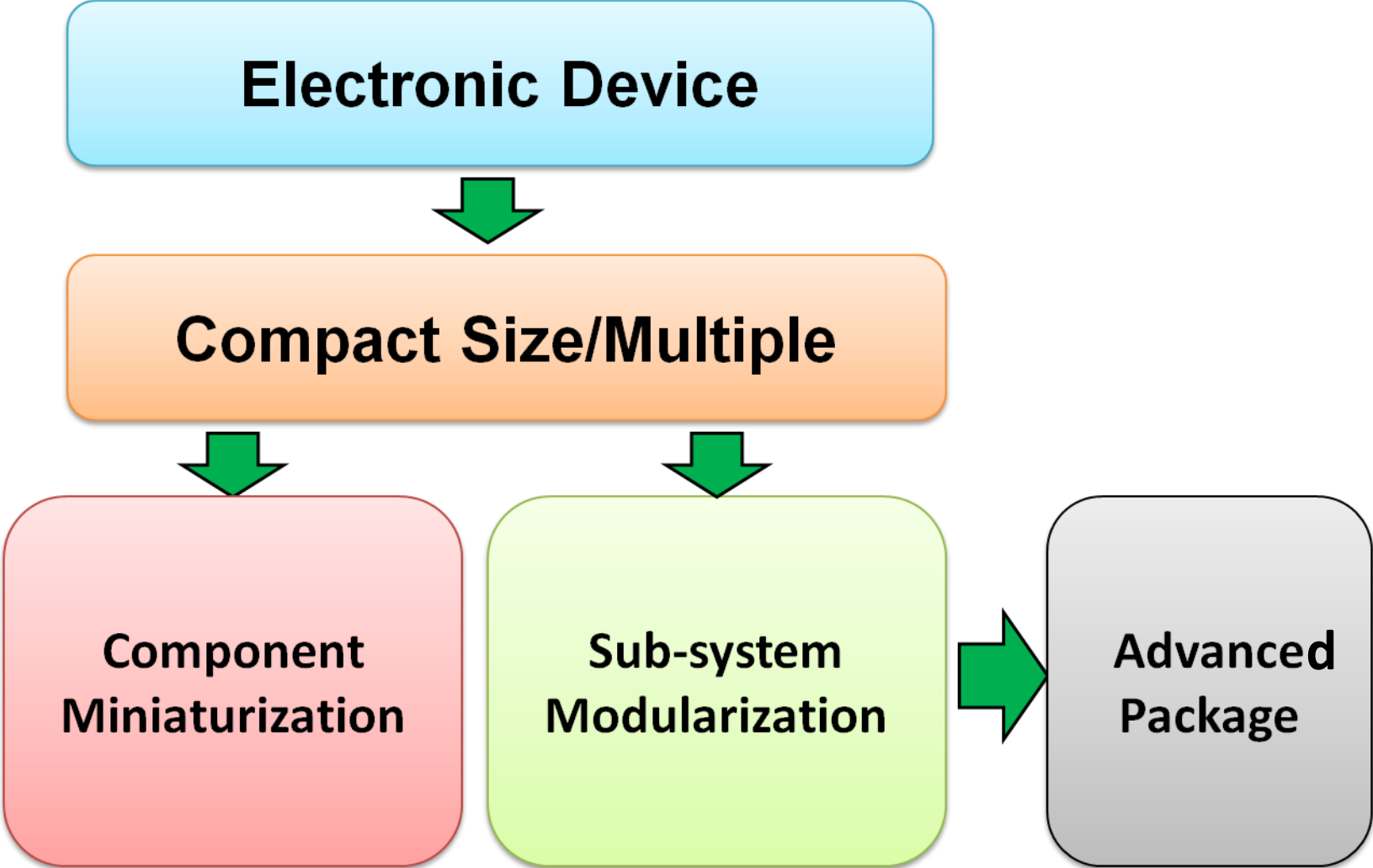
Cutting
Plating
Testing
Winding
Packing



Robotics

Cleaning Robot
Security Robot

Industry Overview



Advanced Package

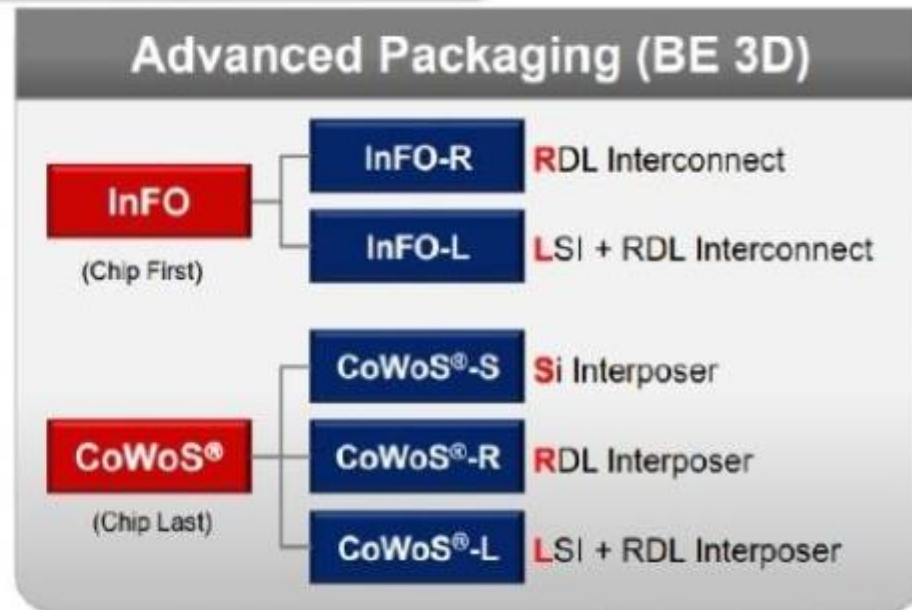
Packaging Type		Manufacturer		Application
SiP (System in Package)		OSAT	ASE	Smart phone
			USI	
		Module house	GIS	
			Luxshare	
		Component	AAC	
			AMS	
3D Package	SoIC	Foundry	TSMC	Smart Phone AI
	InFO,CoWoS		TSMC	
2D/2.5D	Flip chip	OSAT	ASE	Smart Phone IoT Mobile
			Spil	
			Amkor	
			Chipbond	
			Powertech	

TSMC's 3D Fabric

TSMC 3DFabric™



SoIC: System on Integrated Chips

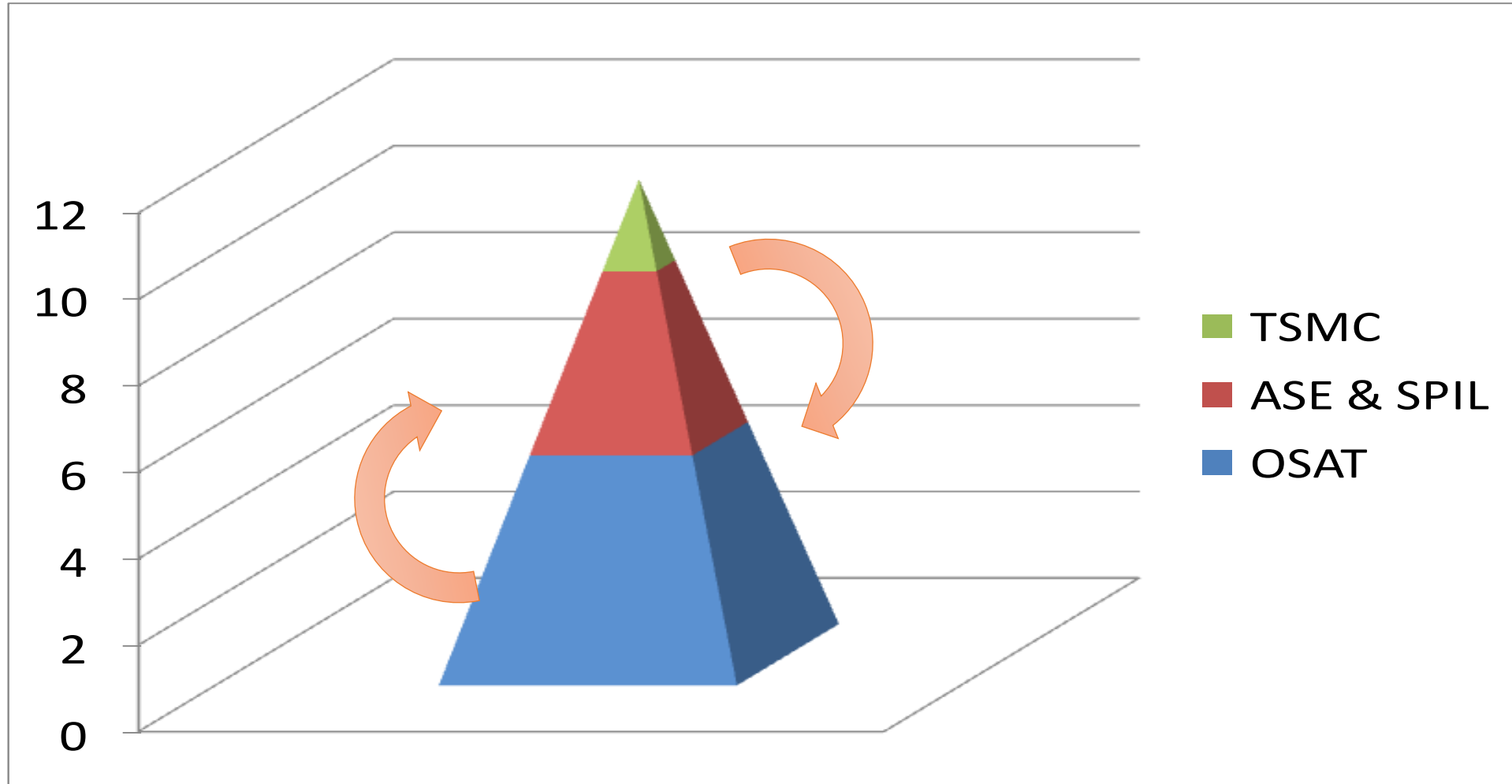


InFO: Integrated Fan-Out
CoWoS: Chip on Wafer on Substrate
RDL: Redistribution Layer
LSI: Local Si Interconnect

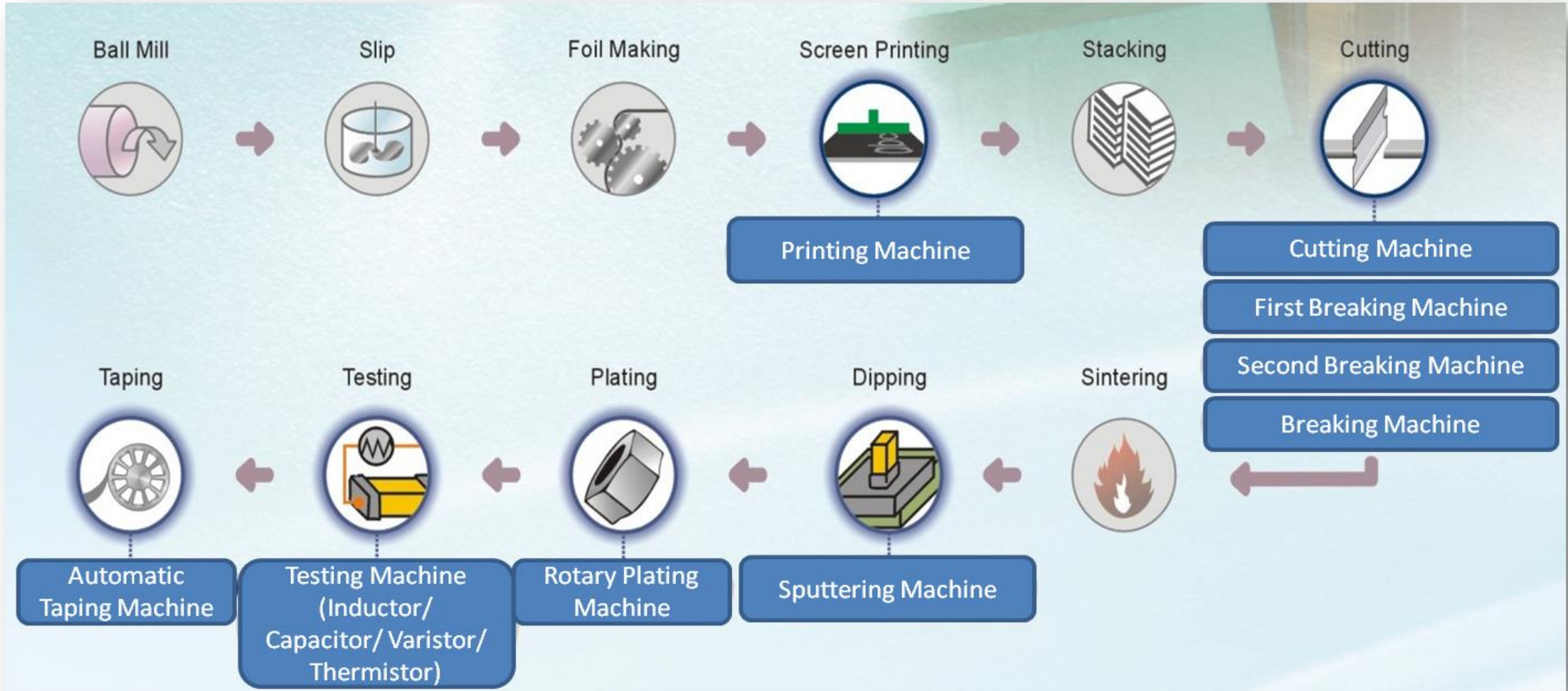
CoWoS Process Flow



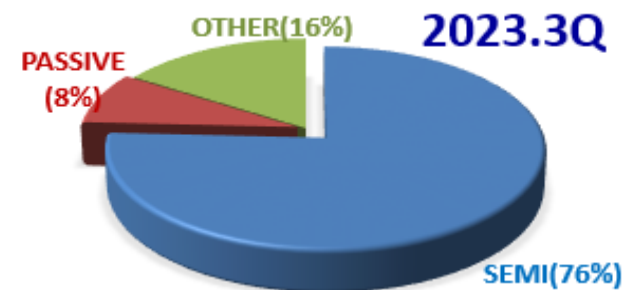
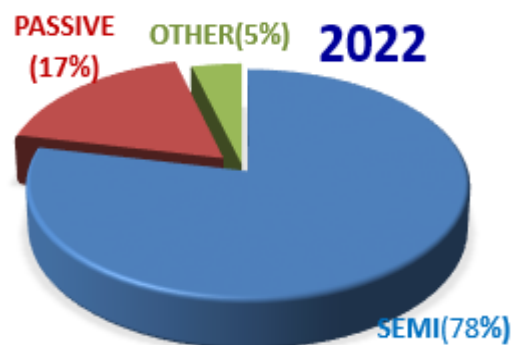
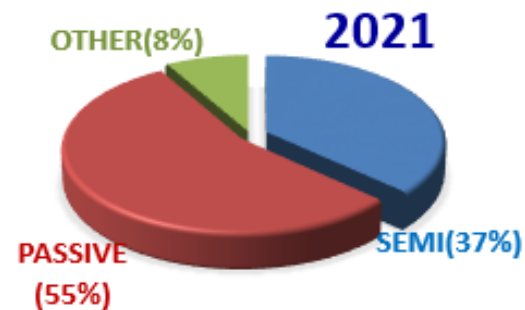
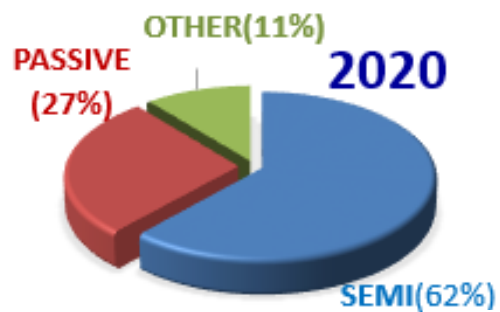
Target



Passive Component Production Process



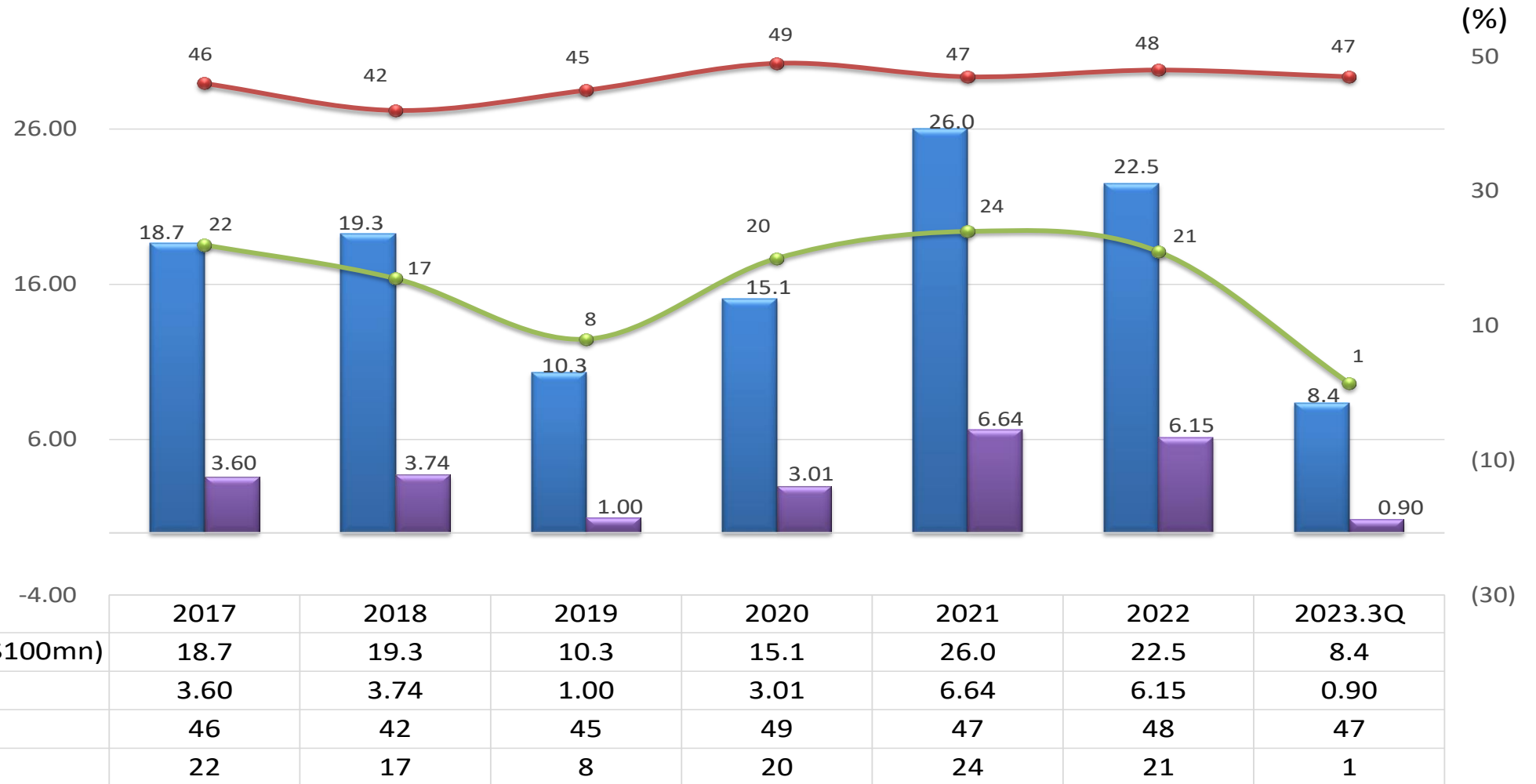
Financial Highlights



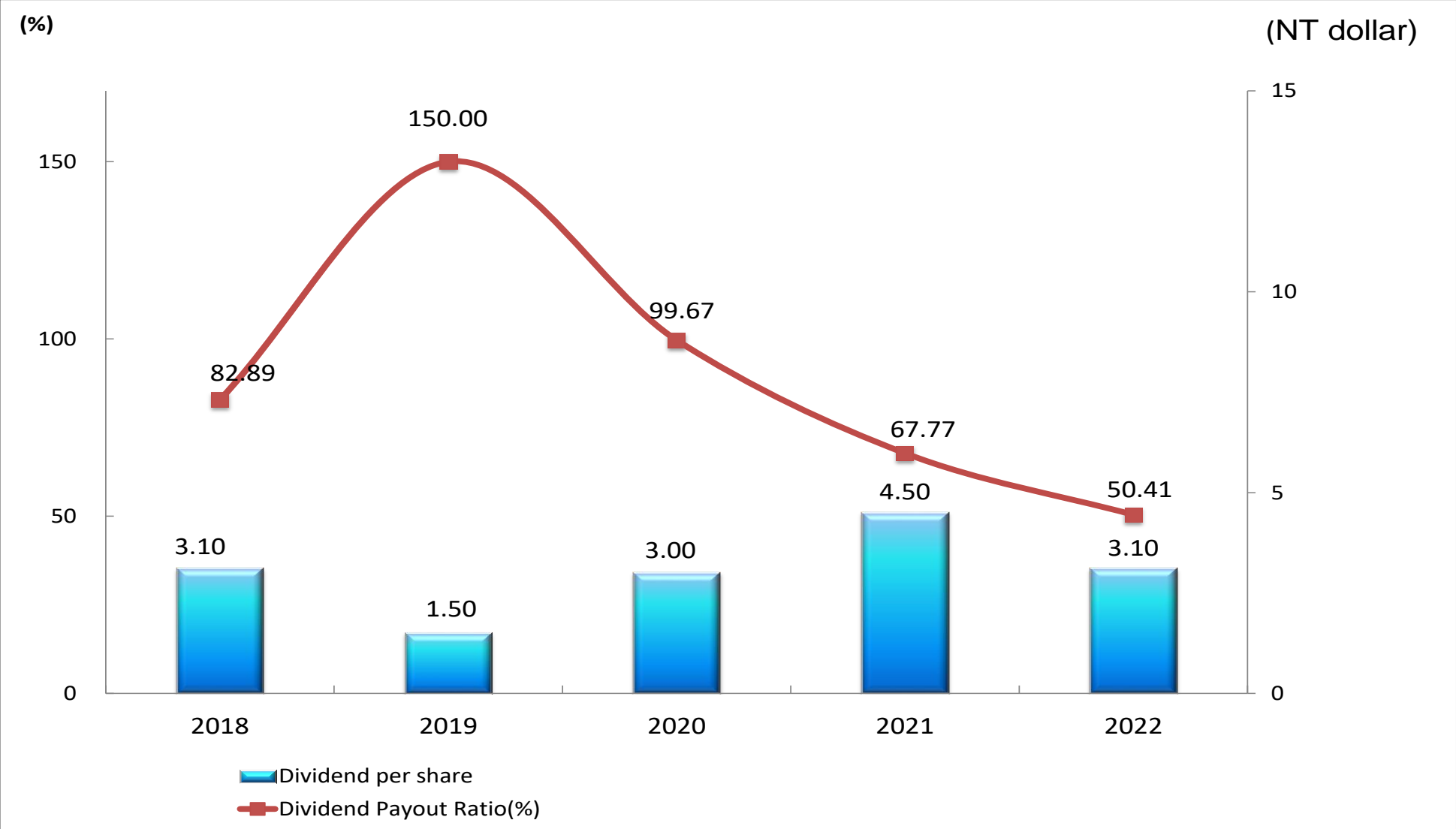
NT\$100M
2023.3Q

	2020		2021		2022		2023.3Q	
SEMI	9.28	62%	9.60	37%	17.63	78%	6.33	76%
PASSIVE	4.14	27%	14.29	55%	3.93	17%	0.70	8%
OTHER	1.64	11%	2.15	8%	0.92	5%	1.32	16%
TOTAL	15.06	100%	26.04	100%	22.48	100%	8.35	100%

Financial Highlights



Financial Highlights





Thank you!